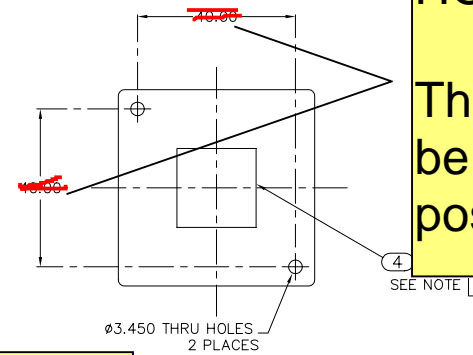
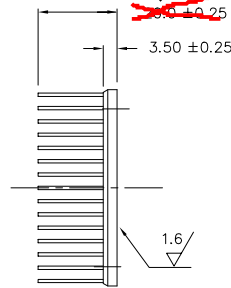
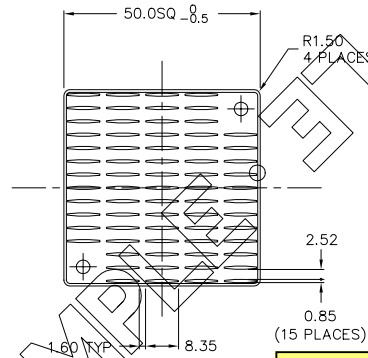


REVISIONS				
REV	DATE	DESCRIPTION	CHG	APPR

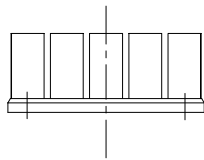
MAXIMUM OVERALL HEIGHT 15.00

HOLE PITCH 44.0x44.0

The hole location should be in other diagonal position (mirror image).



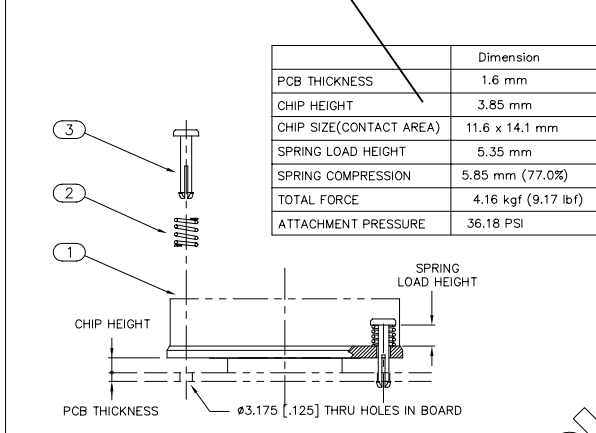
PCB THICKNESS 2.40 mm
CHIP HEIGHT 2.20-2.46
CHIP SIZE 27.0 mm SQ LID
SUBSTRATE 35.0SQ
TARGET LOAD 10PSI OR MORE



NOTES : UNLESS OTHERWISE SPECIFIED

- INTERPRET DIMENSIONS AND TOLERANCES PER ANSI Y14.5M
- ALL DIMENSIONS ARE IN MILLIMETERS [INCHES].
- TOLERANCES :
 .XX ±0.254 [.010]
 .XXX ±0.127 [.005]
 ANGLES ± 1°
- REMOVE ALL BURRS AND BREAK SHARP EDGES. UNSPECIFIED CORNER R0.5 MAX OR C0.5 MAX
- A BEND OF THE FIN: THE FINS MUST NOT CONTACT.
- PEEL ONE SIDE OF LINER FROM THERMAL PAD. ADHERE IN APPROXIMATE POSITION OF THE BASE SURFACE CENTER

ASSEMBLY IMAGE (REFERENCE ONLY / DO NOT SCALE)



④	S001Z03F	<THERMAL INTERFACE> T-PCM905C-20S	Lot# T-PCM905C 20 x 20 mm	1
③	S001YZ0M	<PUSH PIN> PIP3.175x14.3	BRASS (ROHS COMPLIANT) C6801 SAN-ETU METALS BZ5 OR EQUIVALENT	2
②	S001YJ06	<SPRING>	OUTSIDE DIA: 6.15 mm WIRE DIA: .65 mm FREE LENGTH: 11.2 mm SPRING RATE: 3.487 (N/mm2) SOLID HEIGHT: 3.6 mm MATERIAL: Music Wire OR EQUIVALENT	2
①		<HEATSINK> <--HEATSINKNAME-->	MD50 SERIES HEAT SINK MODIFIED 6063 ALUMINUM BLACK ANODIZE	1
ITEM	PART NO.	PART NAME	REMARK	Q'TY
ALPHA CO.,LTD.			CSTM'R'S PART NO.	
MATERIAL			NAME	<--HEATSINK ASSEMBLY NAME-->
SCALE 1 : 1		APPR & CHCK -----	PART NO. & DWG NO. -----	REV
DATE 2008.05.20		DSGN & DWG -----	RDCN:	LOFF: